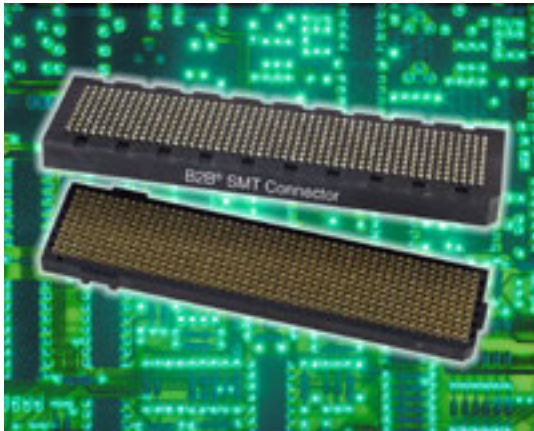


Connector Line



Advanced Interconnections Corporation introduces the B2B® high density SMT connector line, which is now available in a 500 position footprint on 1.27 mm pitch. Designed for high I/O board to board applications where durability and reliability are critical, such as servers and routers, the latest member of the B2B SMT Connector series is available in a standard mated height of 6.00 mm and offers low insertion and withdrawal forces. The line employs screw-machined terminals with multi-finger contacts and a solder ball terminal design; field-proven for reliability and processing results. With a current rating of 3 Am/s per pin, more contacts can be assigned to data/signal transfer (fewer pins are sacrificed for power/ground). These high quality terminals, coupled with a precision molded LCP insulator, offer a more rugged and durable contact system that is better suited for blind mating applications.

www.advanced.com 800-424-9850

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